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Product / Process Change Notification (PCN)

☐ Major change
☒ Minor change

PCN #:	PCN_IndPDA_20211115
Affected Series:	WE-PDA; 784771xxx; 784770xxx; 7847709xxx
PCN Date:	October 08, 2021
Effective Date:	November 15, 2021

Change Category:

☐ Equipment / Location
☐ General Data
☒ Material
☐ Process
☐ Product Design
☐ Shipping / Packaging
☐ Supplier
☐ Software

Contact:	Product Management
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Data Sheet Change:

☐ Yes ☒ No

Attachment:

☒ Yes ☐ No

DESCRIPTION AND PURPOSE OF CHANGE:

Due to force majeure Würth Elektronik eiSos is forced to release a second source for the lead frame (base copper) material supplier. The electrical and mechanical properties are the same.

All products with date code 2021-10-15 or later, will be affected by this change.

There will be no change in form, fit, function, quality or reliability of the product.

DETAIL OF CHANGE:

The new lead frame material has the same material composition. Therefore, the final product will have the same characteristics regardless of the material to be used. The new material will be handled as a second source to increase capacity and viability for possible future scenarios in the supply chain.

The table below shows the detailed information of the material composition for both material supplier:

Semi-Component	Material acc. ISO 22628/IMDS	Substances	CAS
First Source	Copper Alloys	Copper(cu)	7440-50-8
		Tin(Sn)	7440-31-5
Second Source	Copper Alloys	Copper(cu)	7440-50-8
		Tin(Sn)	7440-31-5

RELIABILITY / QUALIFICATION SUMMARY:

Product approval is according to the AEC-Q200 and is internally released by the Product Management Department.

- Change/Implementation of material: Test 22 “Terminal Strength”, Test 9 “External Visual”, Test 19 “Resistance to soldering heat”, Test 18 “Solderability”, Test 21 “Board Flex”.